



SOT486-1

plastic low profile quad flat package; 144 leads; body 20 x 20 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP144
Package type industry code	LQFP144
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E23
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	19.9	-	20	20.1	mm
E	package width	19.9	-	20	20.1	mm
A	seated height	[tbd]	-	1.6	1.6	mm
A ₂	package height	1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination	-	-	144	-	



2. Package outline

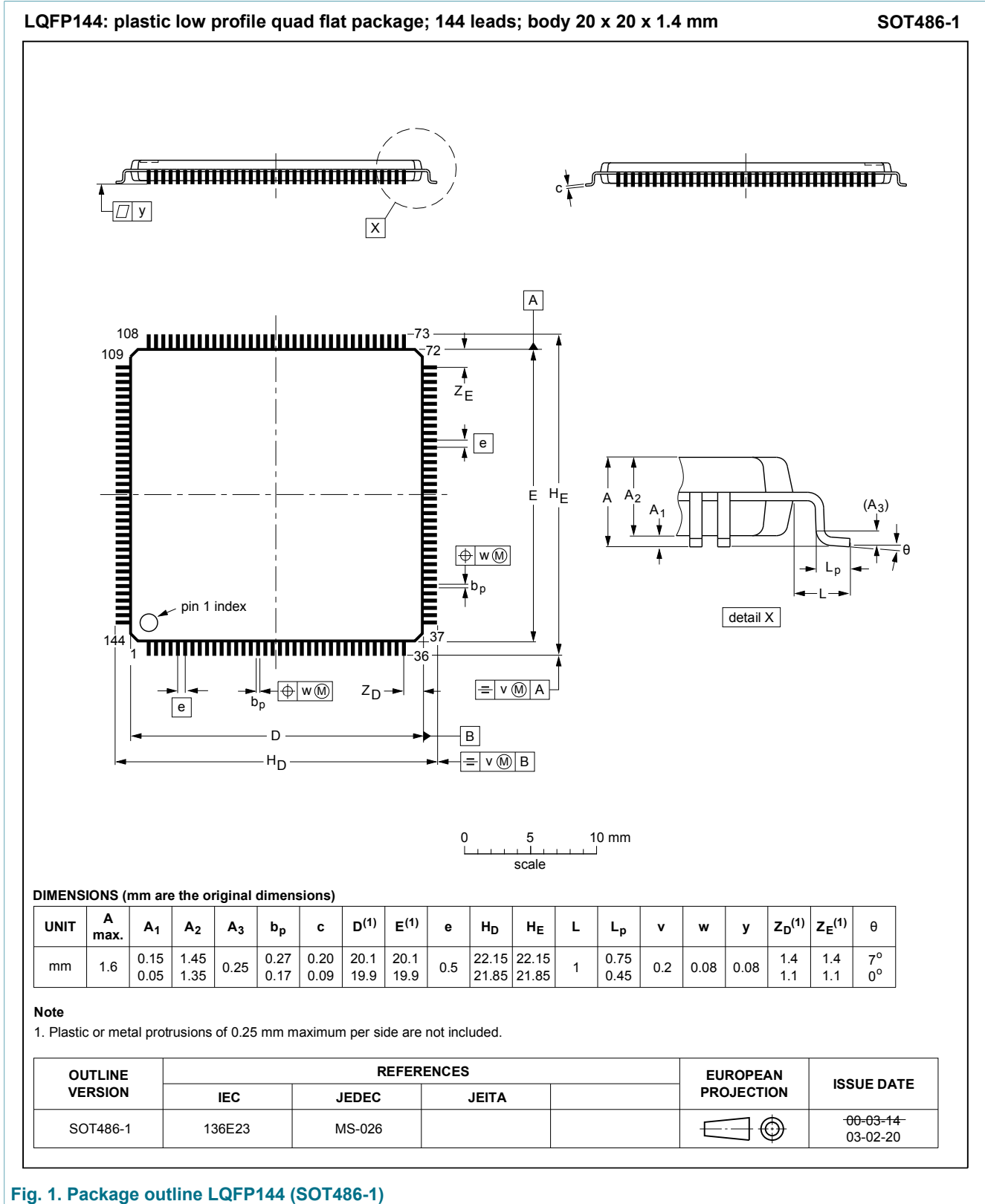


Fig. 1. Package outline LQFP144 (SOT486-1)

3. Soldering

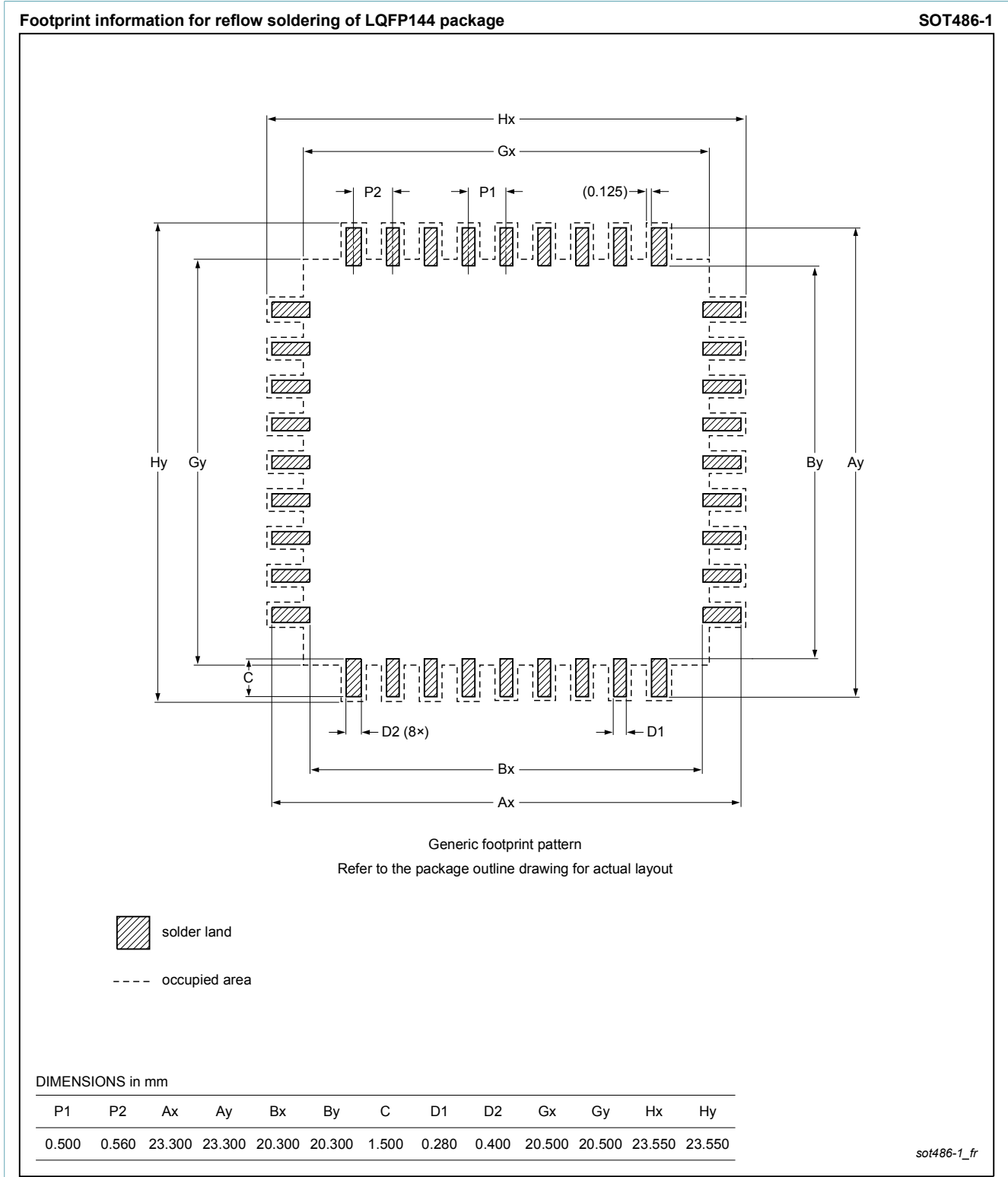


Fig. 2. Reflow soldering footprint for LQFP144 (SOT486-1)

4. Legal information

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Date of release: 8 February 2016
